



Description

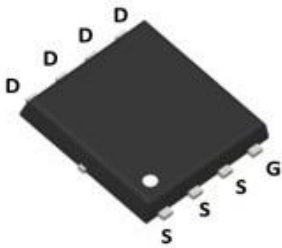
Features

- Extremely Low RDS(on):4.0mΩ
@V_{GS}=10 V, I_D=40 A
 - Good stability and uniformity
 - 100% avalanche tested
- Excellent package for good heat dissipation

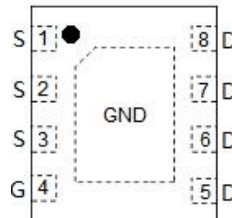
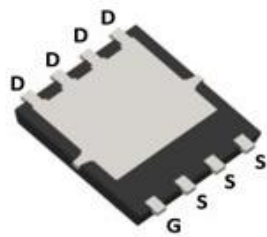
General Description

The 3080 uses advanced trench Typ.RDS(on) = 4.0 mΩ technology to provide excellent RDS(ON), low gate charge This device is suitable for use in UPS, power switching and general purpose applications.

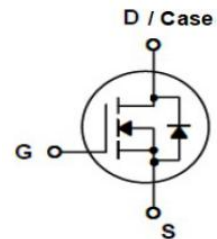
Package



PDFN5×6-8L



Marking and pin Assignment



Schematic Diagram

Thermal Characteristics

Symbol	Parameter	Value	Units
R _{θJC}	Thermal Resistance, Junction-to-Case	2.01	°C/W

Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

Symbol	Parameter	Value	Units
V _{DS}	Drain-Source Voltage	30	V
I _D	Drain Current - Continuous (TC= 25°C)	80	A
	- Continuous (TC= 100°C)	45*	A
I _{DM}	Drain Current - Pulsed (Note 1)	185*	A
V _{GS}	Gate-Source Voltage	± 20	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	196	mJ
P _D	Power Dissipation (TC = 25°C)	76	W
	- Derate above 25°C	0.52	W/°C
T _j , T _{stg}	Operating and Storage Temperature Range	-55 to +168	°C

* Drain current limited by maximum junction temperature



Electrical Characteristics (TC = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units	
Off Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	30			V	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			1	μA	
I_{GSSF}	Gate Leakage Current, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$			100	nA	
I_{GSSR}	Gate Leakage Current, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$			-100	nA	
On Characteristics							
$V_{GS(TH)}$	Gate Threshold voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1	1.5	2	V	
$R_{DS(on)}$	Drain-Source on-state resistance	$V_{GS} = 10\text{ V}, I_D = 40\text{ A}$		4.0	5.2	m Ω	
		$V_{GS} = 4.5\text{ V}, I_D = 24\text{ A}$		5.8	8.5	m Ω	
gFS	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 24\text{ A(} \text{Note 3)}$	20			S	
Dynamic Characteristics							
C_{iss}	Input capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V},$ $F=1.0\text{Mhz}$		1860		pF	
C_{oss}	Output capacitance			242		pF	
C_{rss}	Reverse transfer capacitance			218		pF	
Switching Characteristics							
$t_{d(on)}$	Turn On Delay Time	$V_{DD}=15\text{V}, I_D=60\text{A},$ $V_{GS}=4.5\text{V}, R_G=1.80\Omega$ (Note 3, 4)		11.5		ns	
t_r	Rising Time			164		ns	
$t_{d(off)}$	Turn Off Delay Time			12.8		ns	
t_f	Fall Time			81		ns	
Q_g	Total Gate Charge		$V_{DD}=15\text{V}, I_D=30\text{A},$		40		nC
Q_{gs}	Gate-Source Charge		$V_{GS}=10\text{V}$		5.6		nC
Q_{gd}	Gate-Drain Charge		(Note 3, 4)		9.8		nC
Drain-Source Diode Characteristics and Maximum Ratings							
I_S	Maximum Continuous Drain-Source Diode Forward Current				80	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current				185	A	
V_{SD}	Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 24\text{ A}$			1.2	V	
T_{rr}	Reverse recovery time	$I_F=60\text{A}, di/dt=100\text{A}/\mu\text{S}$		14		ns	
Q_{rr}	Reverse recovery charge			2.6		nC	

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 0.5\text{ mH}, I_{AS} = 35\text{ A}, V_{DD} = 20\text{ V}, R_G = 25\ \Omega$, Starting $T_j = 25^\circ\text{C}$
3. $I_{SD} \leq 40\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_j = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\ \mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature



Typical Performance Characteristics

Figure 1: Output Characteristics

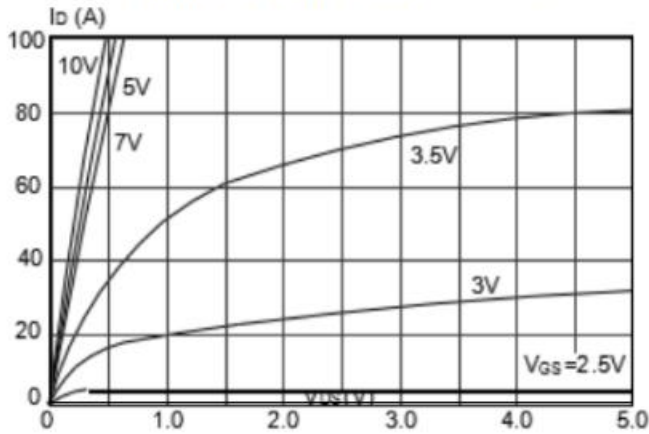


Figure 2: Typical Transfer Characteristics

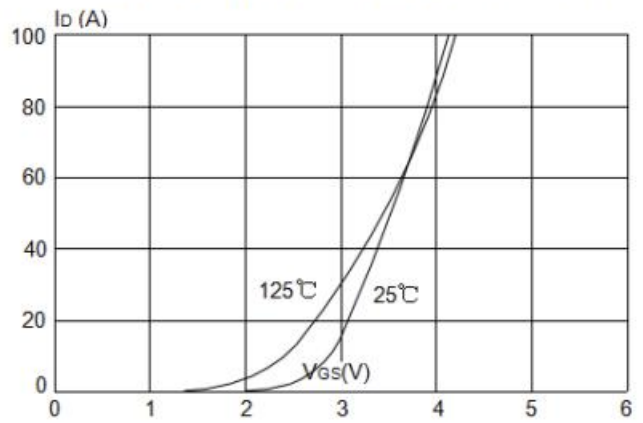


Figure 3: On-resistance vs. Drain Current

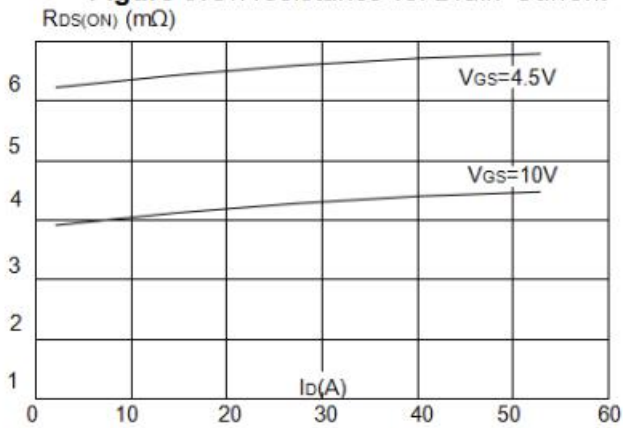


Figure 4: Body Diode Characteristics

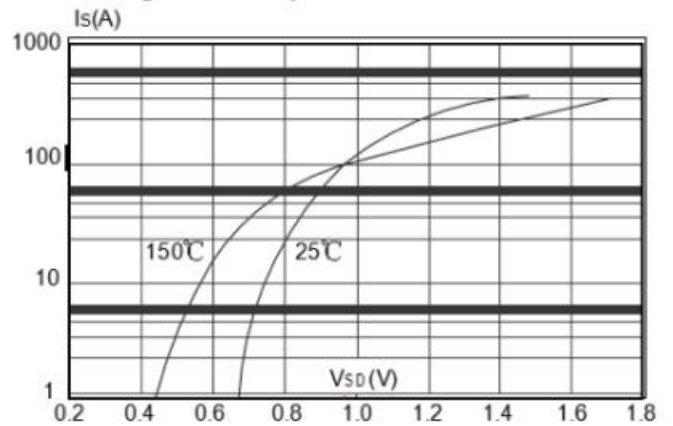


Figure 5: Gate Charge Characteristics

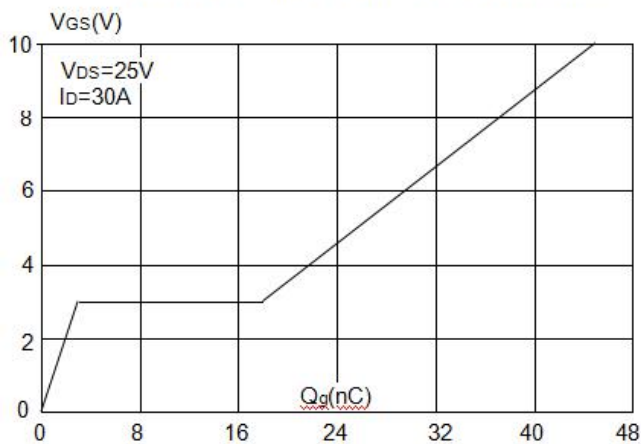


Figure 6: Capacitance Characteristics

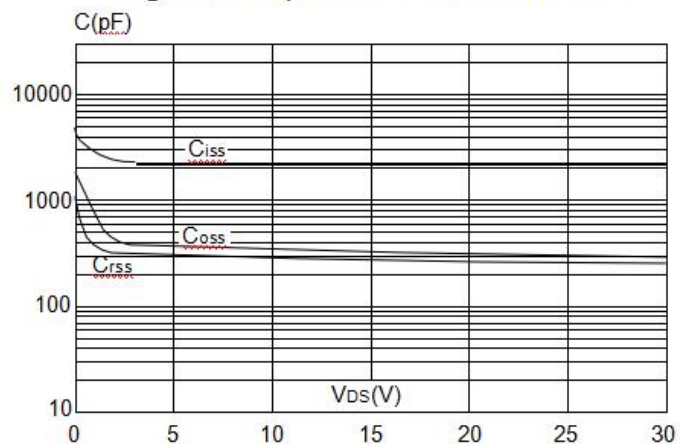




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

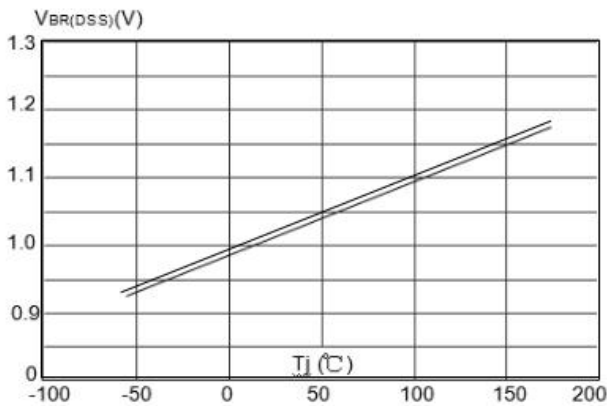


Figure 9: Maximum Safe Operating Area

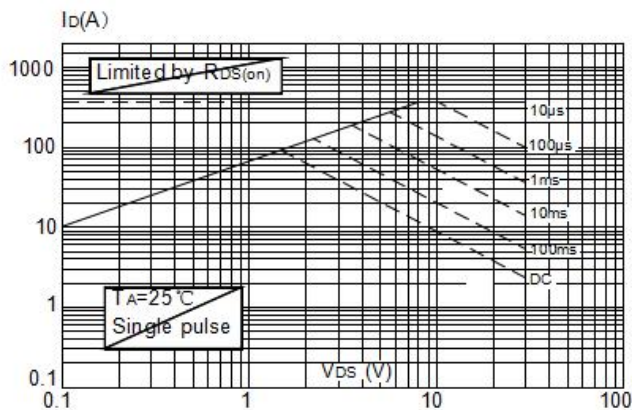


Figure 8: Normalized on Resistance vs. Junction Temperature

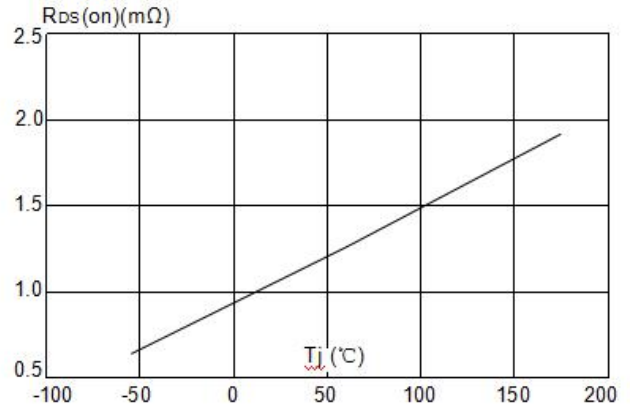


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

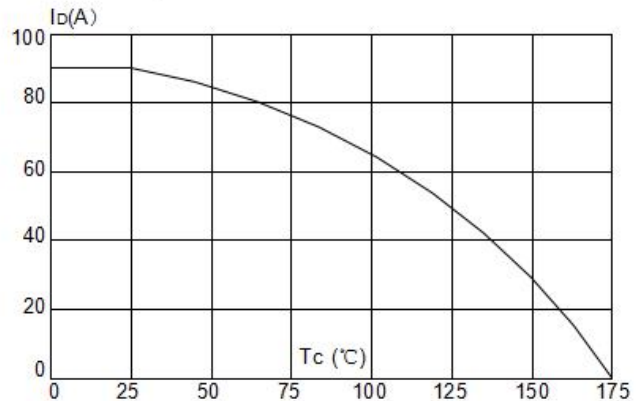
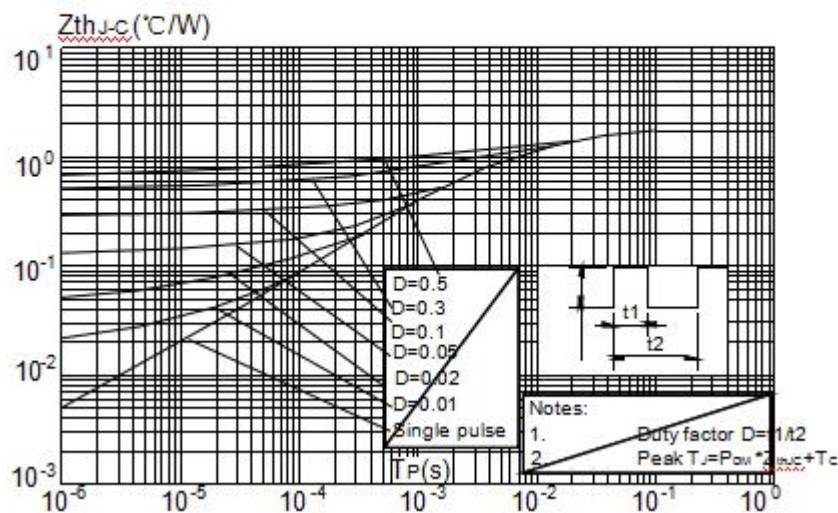
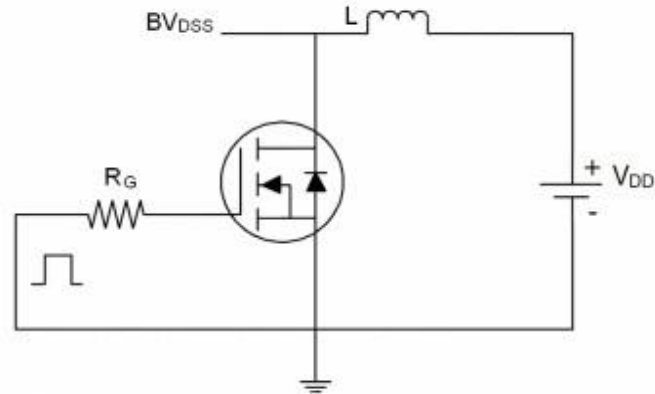


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-252)

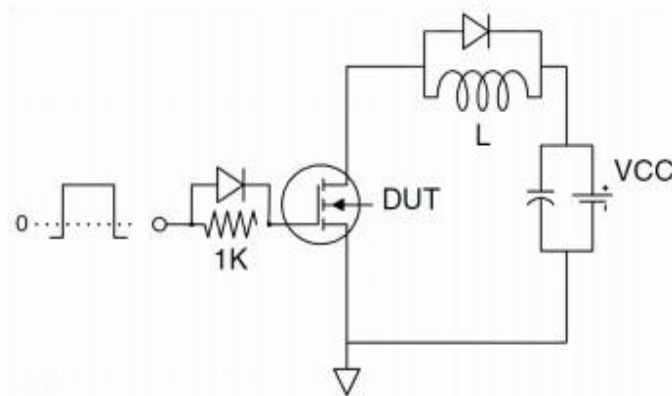


Test Circuit

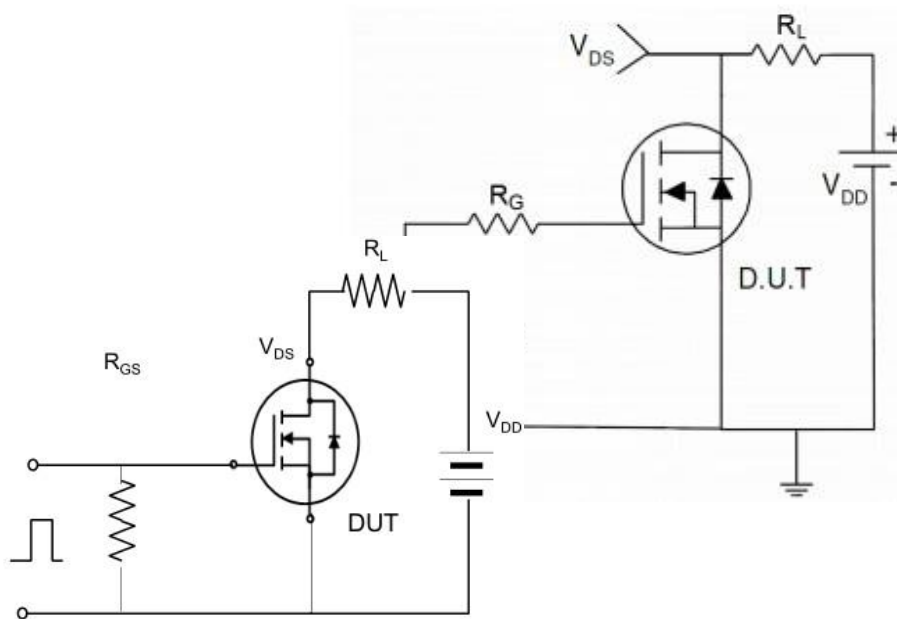
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit:

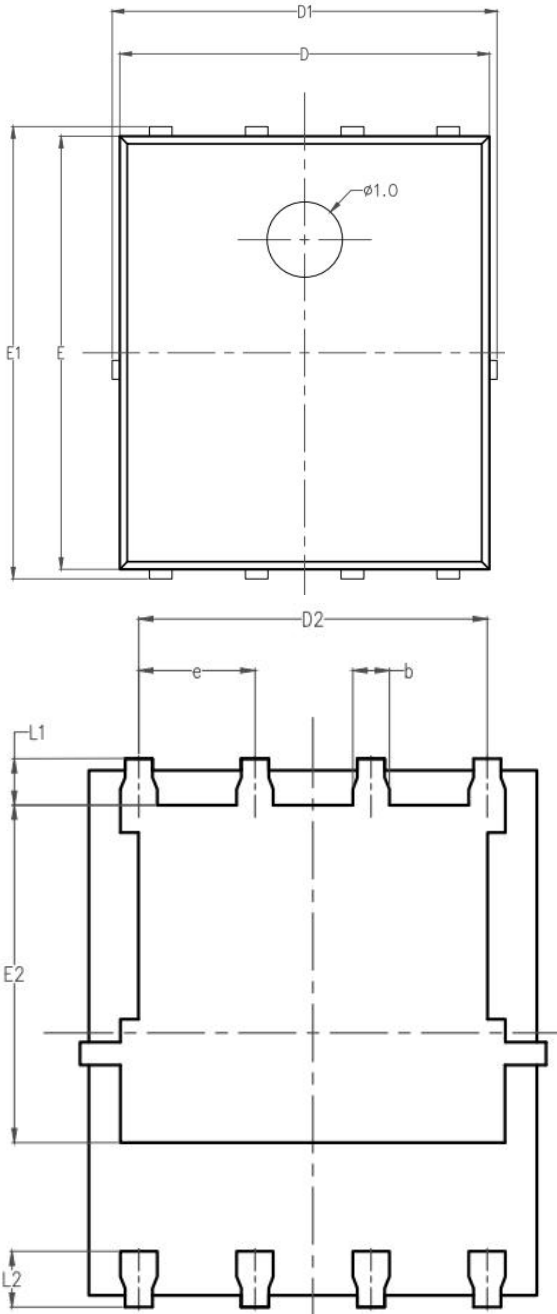


3) Switch Time Test Circuit:





PDFN5x6-8L Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.95	1.00	1.05
A1	0.254REF.		
b	0.41	0.46	0.51
D	4.85	4.90	4.95
D1	4.90	5.00	5.10
D2	3.766	3.816	3.866
E	5.696	5.746	5.796
E1	5.95	6.00	6.05
E2	3.525	3.575	3.625
e	1.22	1.27	1.32
L1	0.46	0.51	0.56
L2	0.56	0.61	0.66